

LISTING OF CLAIMS

The following is a listing of the claims in the application with claims 2 and 10 shown as amended and claims 1 and 6-9 cancelled.

LISTING OF CLAIMS

Claim 1. (Cancelled)

Claim 2. (Currently Amended) ~~The piezoelectric device according to claim 1,~~

A piezoelectric device comprising:

a piezoelectric vibrating reed having excitation electrodes,

a package with outer terminals into which the piezoelectric vibrating reed is mounted; and

a strip of insulating material having electrical conductors in the form of wiring patterns disposed thereon for forming an insulating bonding ("TAB") tape, with said TAB tape being interposed in said package such that the excitation electrodes of said piezoelectric vibrating reed are interconnected to the outer terminals of the package through the conductive wiring patterns on said TAB tape,

wherein said TAB tape includes a opening or a plurality of openings in the form of windows extending therethrough;

wherein the wiring patterns are formed on a surface of insulating tape facing mounting electrodes;

wherein the wiring patterns are formed on the surface of the insulating tape with portions of the wiring patterns overlying the windows; and

wherein the piezoelectric vibrating reed is mounted on the TAB tape with the excitation electrodes connected to the wiring pattern via said windows.

Claim 3. (Original) The piezoelectric device according to claim 2,

wherein said TAB tape includes mounting terminals upon which the piezoelectric vibrating reed is mounted with said mounting terminals composed of a portion of said wiring patterns extended from said surface for connection to said excitation electrodes.

Claim 4. (Original) The piezoelectric device according to claim 3,

wherein the mounting terminals are located in an elevated plane spaced apart from the plane of said TAB tape

Claim 5. (Original) The piezoelectric device according to claim 2,

wherein the TAB tape is connected to the piezoelectric vibrating reed in the package by means of bumps of conductive material or solder.

Claims 6 - 9 (Cancelled)

Claim 10. (Currently Amended) ~~The piezoelectric device according to claim 1,~~

A piezoelectric device comprising:

a piezoelectric vibrating reed having excitation electrodes,

a package with outer terminals into which the piezoelectric vibrating reed is mounted; and

a strip of insulating material having electrical conductors in the form of wiring patterns disposed thereon for forming an insulating bonding ("TAB") tape, with said TAB tape being interposed in said package such that the excitation electrodes of said piezoelectric vibrating reed are interconnected to the outer terminals of the package through the conductive wiring patterns on said TAB tape,

wherein said TAB tape includes mounting terminals upon which the piezoelectric vibrating reed is mounted with said mounting terminals composed of a portion of said wiring patterns extended from said surface for connection to said excitation electrodes.

Claim 11. (Original) The piezoelectric device according to claim 10,

wherein the mounting terminals are located in an elevated plane spaced apart from the plane of said TAB tape.

Claim 12. (Original) The piezoelectric device according to claim 10,

wherein the TAB tape is connected to the piezoelectric vibrating reed in the package by means of bumps of conductive material or solder.